N-CHANNEL ENHANCEMENT MODE POWER MOSFET

SGT MOS、低内阻、低结电容开关损耗小

TF020N06NG

● General Description

The TF020N06NG uses advanced trench technology and design to provide excellent RDS(ON) withlowgate charge. It can be used in a wide variety ofapplications.

● Features

Advance device constructure

Low $R_{DS(ON)}$ to minimize conduction loss

Low Gate Charge for fast switching

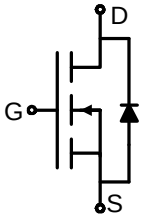
Low Thermal resistance

●Application

Synchronous Rectification for AC-DC/DC-DC converter

Power Tools

● Product Summary

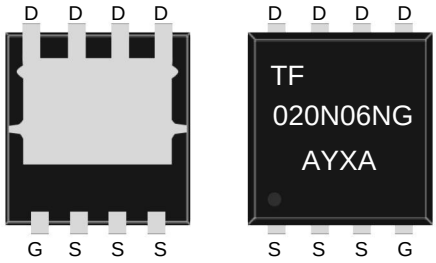


V_{DS} =60V I_D=150A

$R_{DS(10V\ TYP)}$ =1.9mΩ

$R_{DS(4.5V\ TYP)}$ =2.6mΩ

RoHS compliant



PDFNWB5x6-8L

●Package Marking and Ordering Information:

Part NO.	TF020N06NG
Marking1	020N06NG:TF020N06NG
Marking2	TF:tuofeng; Y:year code; X:Week; AA:device code;
Basic ordering unit (pcs)	5000

●Absolute Maximum Ratings (T_C =25℃)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	$I_{D@}$TC=25℃	150	A
	$I_{D@}$TC=75℃	105	A
	$I_{D@}$TC=100℃	90	A
Pulsed Drain Current ①	I_{DM}	450	A
Total Power Dissipation	P_D@TC=25℃	90	W
Total Power Dissipation	P_D@TA=25℃	3.0	W
Operating Junction Temperature	T_J	-55 to 150	℃
Storage Temperature	T_{STG}	-55 to 150	℃
Single Pulse Avalanche Energy	E_{AS}	155	mJ

●Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	1.5	°C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	3.5	°C/W
Soldering temperature, wavesoldering for 8 s	T_{sold}	-	-	265	°C

●Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS} =0V,I_D =250uA	60	-	-	V
Gate Threshold Voltage	$V_{GS(TH)}$	V_{GS} =V_{DS}, I_D =250uA	1.1	1.5	2.1	V
Drain-Source Leakage Current	I_{DSS}	V_{DS}=60 V_{GS} =0V	-	-	1.0	uA
Gate- Source Leakage Current	I_{GSS}	V_{GS}=±20V ,V_{DS} =0V	-	-	±100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=30A	-	1.9	3.0	mΩ
		V_{GS}=4.5V, I_D=20A	-	2.6	4.0	mΩ
Forward Transconductance	g_{FS}	V_{DS} =25V, I_D=30A	-	35	-	S
Source-drain voltage	V_{SD}	Is=30A	-	0.81	1.20	V

●Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	Ciss	f = 1MHz V_{DS}=30V V_{GS} = 0V	-	5200	-	pF
Output capacitance	Coss		-	1170	-	
Reverse transfer capacitance	Crss		-	95.0	-	

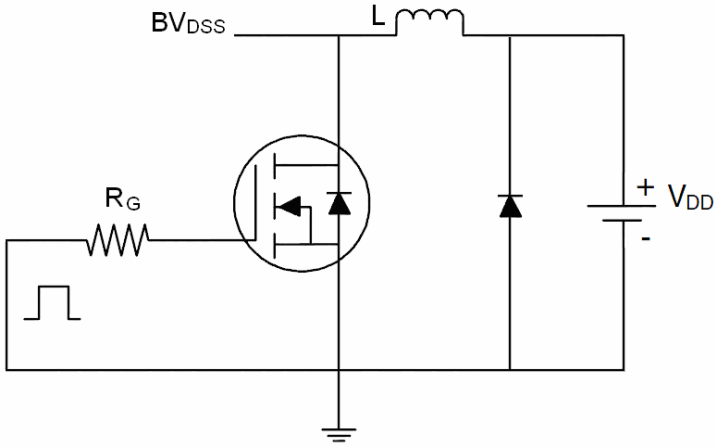
●Switching Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Turn-on delay time	td(on)	V_{DD} = 30V I_D = 30A R_G =3.0Ω V_{GS} = 10V	-	18	-	nS
Rise time	tr		-	16	-	
Turn-off delay time	td(off)		-	18	-	
Fall time	tf		-	11	-	
Total gate charge	Qg	V_{DD} = 30V I_D = 30A V_{GS} = 10V	-	75	-	nC
Gate - Source charge	Qgs		-	18	-	
Gate - Drain charge	Qgd		-	15	-	

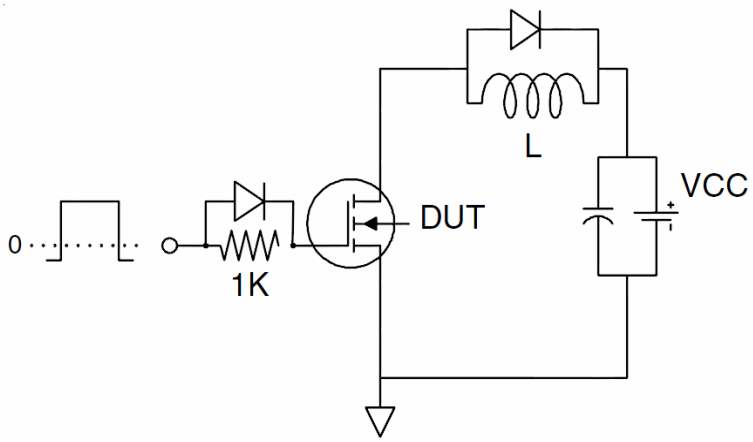
Note: ① Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% ;

Test Circuit

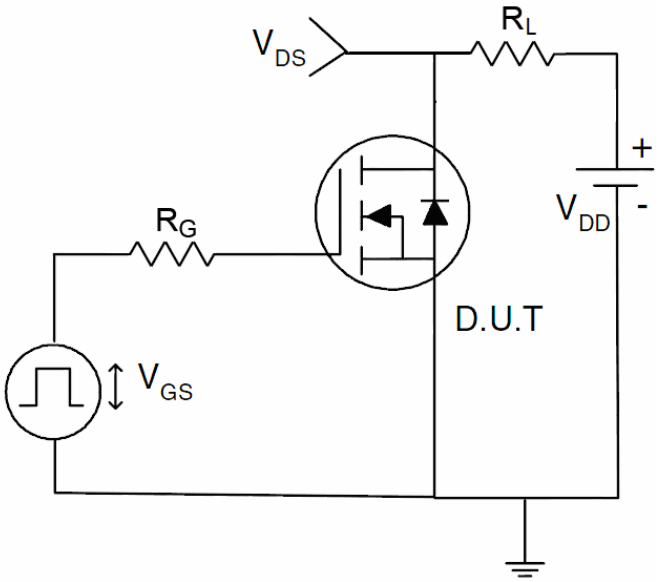
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics

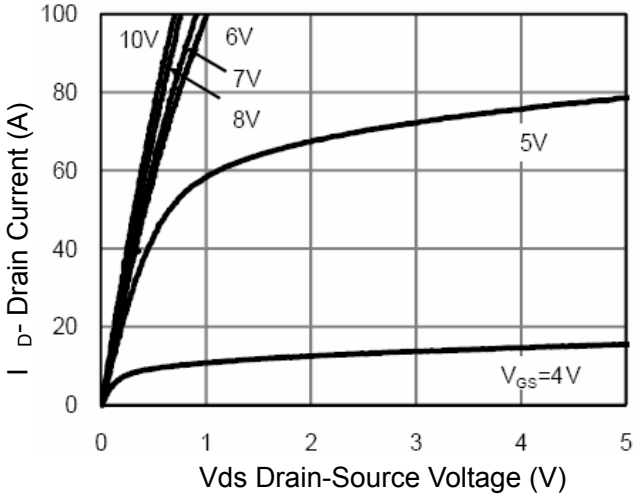


Figure 1 Output Characteristics

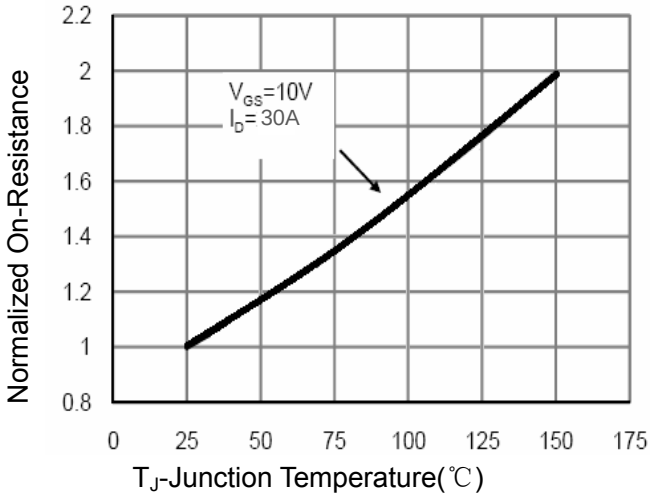


Figure 4 Rdson-JunctionTemperature

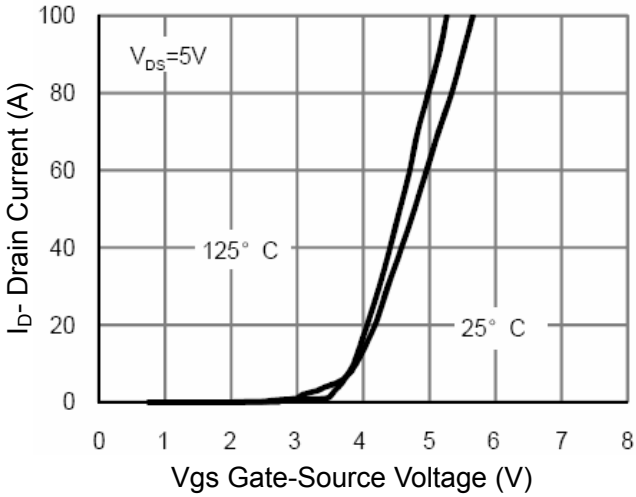


Figure 2 Transfer Characteristics

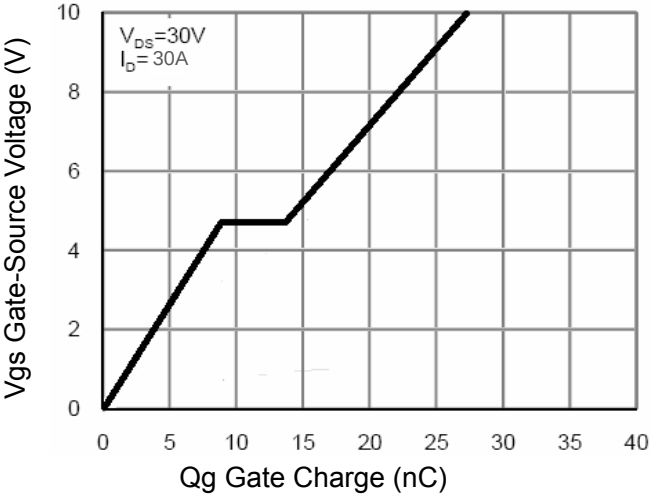


Figure 5 Gate Charge

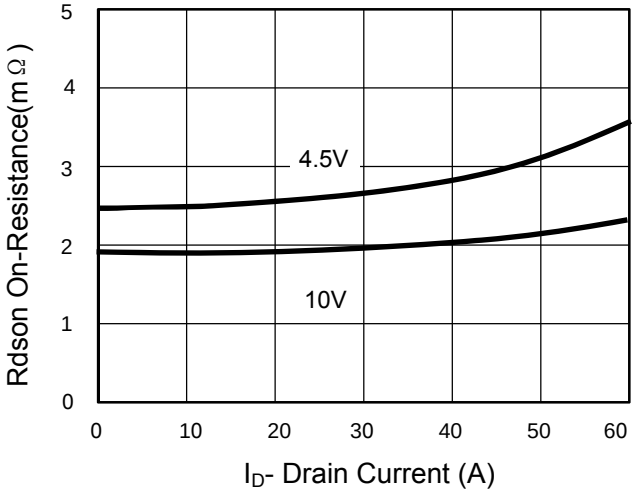


Figure 3 Rdson- Drain Current

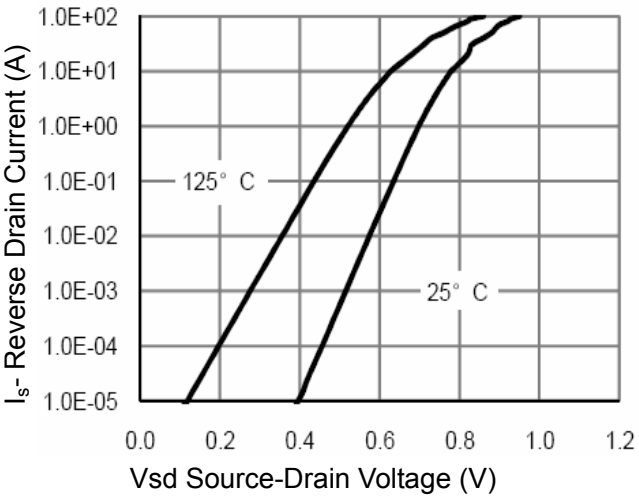


Figure 6 Source- Drain Diode Forward

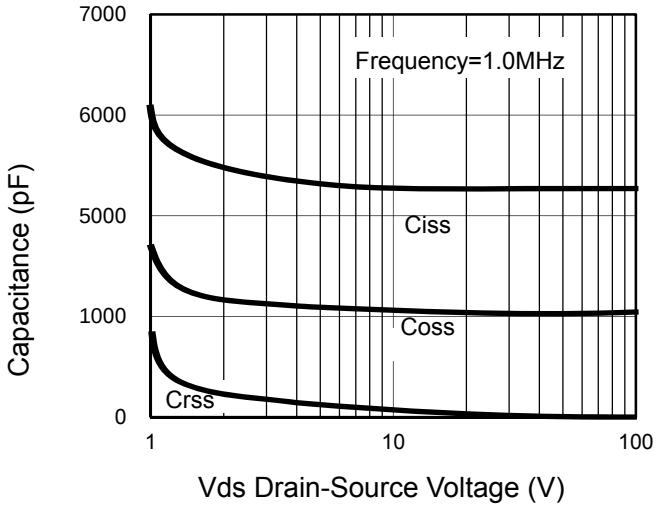


Figure 7 Capacitance vs Vds

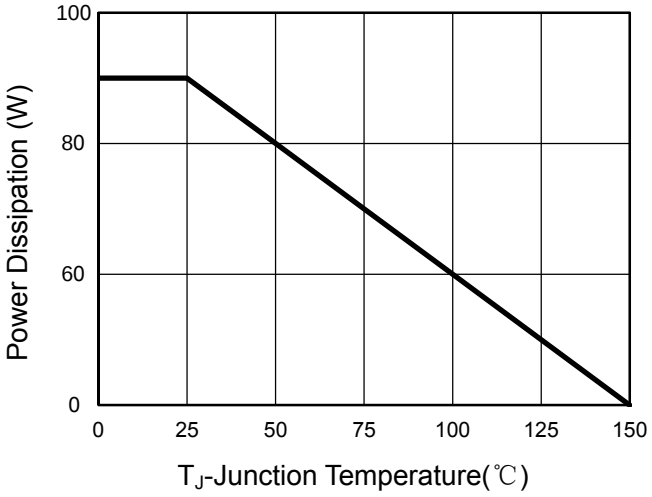


Figure 9 Power De-rating

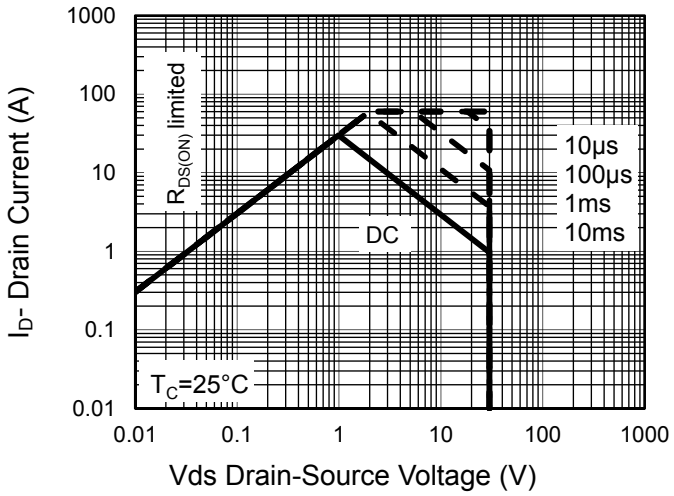


Figure 8 Safe Operation Area

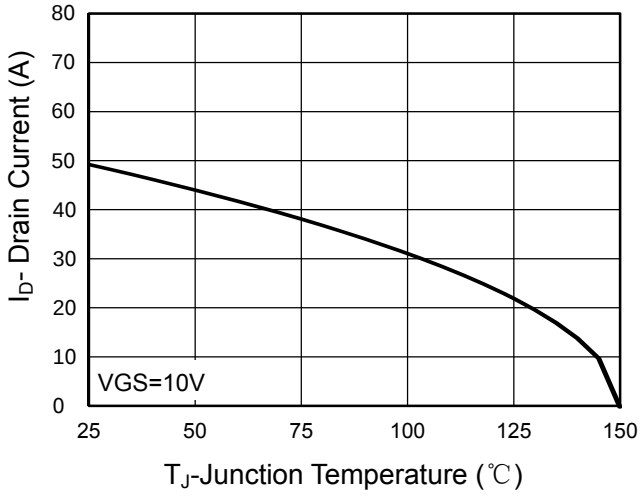


Figure 10 Current De-rating

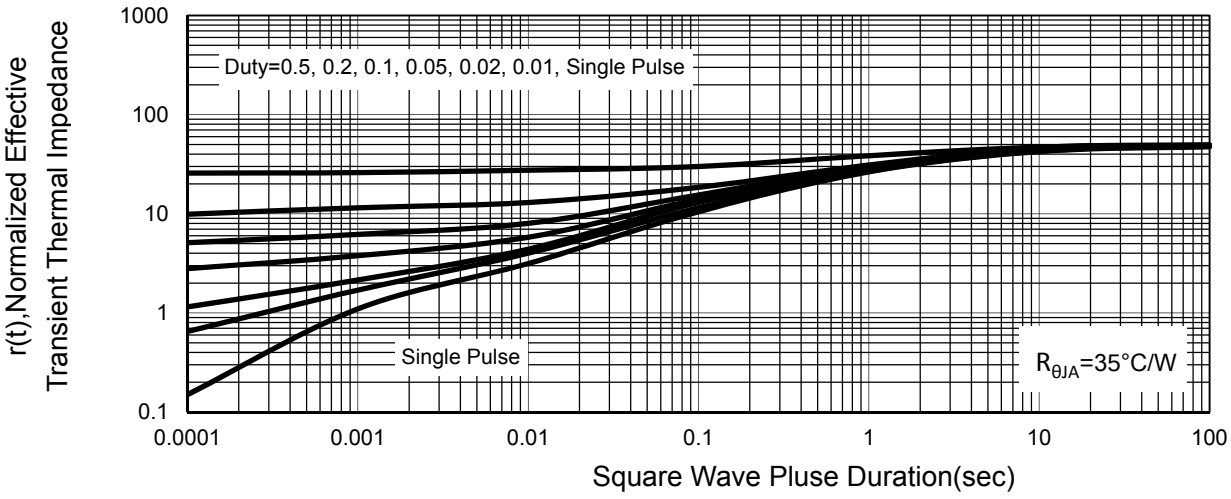
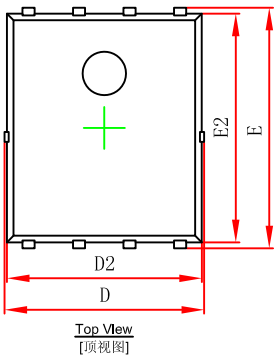
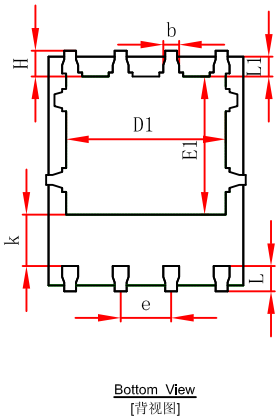
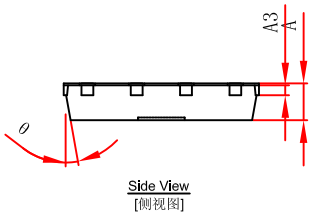


Figure 11 Normalized Maximum Transient Thermal Impedance

PDFNWB5x6-8L Package Outline Dimensions

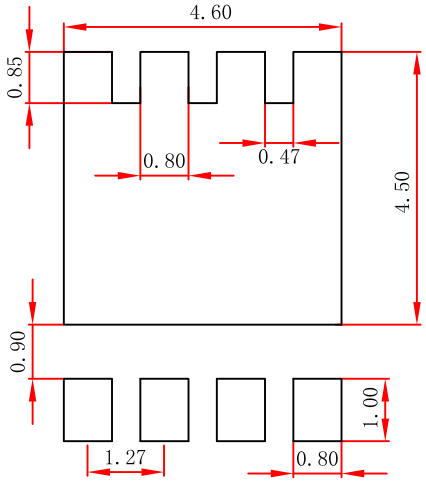






Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°

PDFNWB5x6-8L Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:±0.05mm.
3.The pad layout is for reference purposes only.